

# Advanced Packaging Update: Market and Technology Trends

Vol. 4-0125

This issue of the Advanced Packaging Update features a financial analysis of OSATs. Trends in the semiconductor industry and drivers for the industry are discussed. Growth in AI markets with package examples is included. A five-year market forecast in units is provided. An update on co-packaged optics discusses trends and challenges. A special section is devoted to mobile communications via satellites.

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